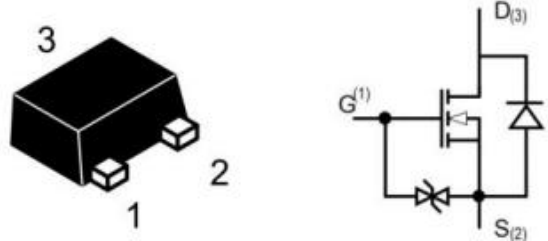


**SOT-723 60V N Channel ESD Protection 沟道带静电保护**  
**MOS Field Effect Transistor 场效应管**



■ **Absolute Maximum Ratings 最大额定值**

Characteristic 特性参数	Symbol 符号	Rat 额定值	Unit 单位
Drain-Source Voltage 漏极-源极电压	$BV_{DSS}$	60	V
Gate- Source Voltage 栅极-源极电压	$V_{GS}$	$\pm 20$	V
Drain Current (continuous)漏极电流-连续	$I_D$ (at $T_A = 25^\circ C$ )	115	mA
Drain Current (pulsed)漏极电流-脉冲	$I_{DM}$	800	mA
Total Device Dissipation 总耗散功率	$P_D$ (at $T_A = 25^\circ C$ )	150	mW
ESD Protected Up to 人体模式静电保护范围	ESD(HBM)	1.0	kV
Thermal Resistance Junction-Ambient 热阻	$R_{\theta JA}$	833	$^\circ C/W$
Junction/Storage Temperature 结温/储存温度	$T_J, T_{stg}$	125, -55~150	$^\circ C$

■ **Applications 应用**

Load Switch 负载开关  
DC/DC Converter 电源转换  
Power management 电源管理  
Battery operated systems 电池工作系统

■ **Device Marking 产品字标**

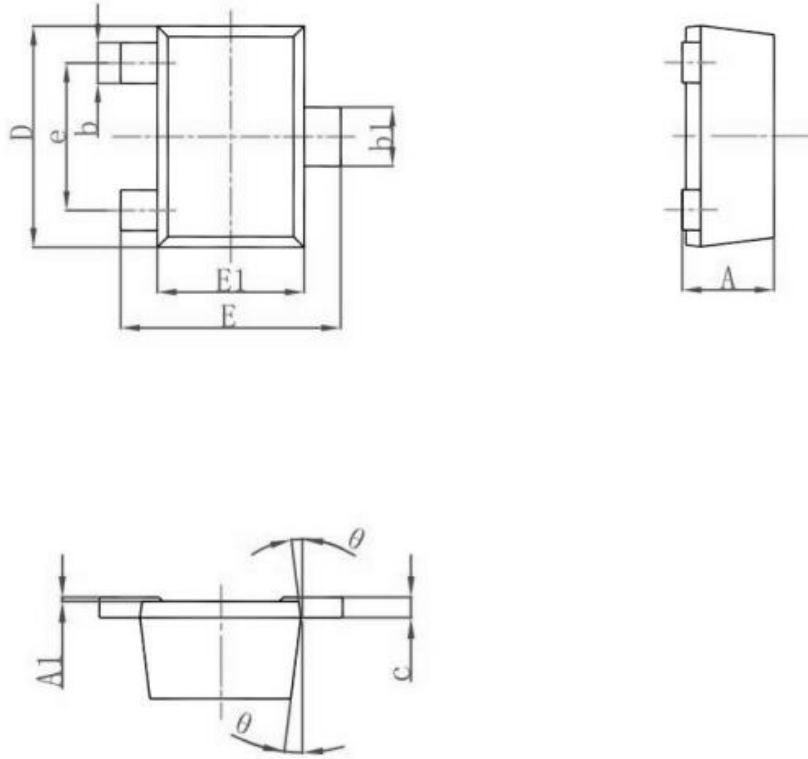
2N7002KM=72K/KN

**Electrical Characteristics 电特性**

 (T<sub>A</sub>=25°C unless otherwise noted 如无特殊说明, 温度为 25°C)

Characteristic 特性参数	Symbol 符号	Min 最小值	Typ 典型值	Max 最大值	Unit 单位
Drain-Source Breakdown Voltage 漏极-源极击穿电压(I <sub>D</sub> =250uA, V <sub>GS</sub> =0V)	BV <sub>DSS</sub>	60	—	—	V
Gate Threshold Voltage 栅极开启电压(I <sub>D</sub> =250μA, V <sub>GS</sub> = V <sub>DS</sub> )	V <sub>GS(th)</sub>	1	1.8	2.5	V
Zero Gate Voltage Drain Current 零栅压漏极电流(V <sub>GS</sub> =0V, V <sub>DS</sub> = 48V)	I <sub>DSS</sub>	—	—	1	uA
Gate Body Leakage 栅极漏电流(V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V)	I <sub>GSS</sub>	—	—	±10	uA
Static Drain-Source On-State Resistance 静态漏源导通电阻(I <sub>D</sub> =300mA, V <sub>GS</sub> =10V) (I <sub>D</sub> =300mA, V <sub>GS</sub> =5V)	R <sub>DS(ON)</sub>	—	—	3 3.5	Ω
Diode Forward Voltage Drop 内附二极管正向压降(I <sub>SD</sub> =150mA, V <sub>GS</sub> =0V)	V <sub>SD</sub>	—	—	1.2	V
Input Capacitance 输入电容 (V <sub>GS</sub> =0V, V <sub>DS</sub> =10V, f=1MHz)	C <sub>ISS</sub>	—	40	—	pF
Common Source Output Capacitance 共源输出电容(V <sub>GS</sub> =0V, V <sub>DS</sub> =10V, f=1MHz)	C <sub>OSS</sub>	—	30	—	pF
Reverse Transfer Capacitance 反馈电容(V <sub>GS</sub> =0V, V <sub>DS</sub> =10V, f=1MHz)	C <sub>RSS</sub>	—	10	—	pF
Total Gate Charge 栅极电荷密度 (V <sub>DS</sub> =30V, I <sub>D</sub> =200mA, V <sub>GS</sub> =10V)	Q <sub>g</sub>	—	1.6	—	nC
Gate Source Charge 栅源电荷密度 (V <sub>DS</sub> =30V, I <sub>D</sub> =200mA, V <sub>GS</sub> =10V)	Q <sub>gs</sub>	—	0.5	—	nC
Gate Drain Charge 栅漏电荷密度 (V <sub>DS</sub> =30V, I <sub>D</sub> =200mA, V <sub>GS</sub> =10V)	Q <sub>gd</sub>	—	0.3	—	nC
Turn-ON Delay Time 开启延迟时间 (V <sub>DS</sub> =30V I <sub>D</sub> =200mA, R <sub>GEN</sub> =3.3 Ω, V <sub>GS</sub> =10V)	t <sub>d(on)</sub>	—	10	—	ns
Turn-ON Rise Time 开启上升时间 (V <sub>DS</sub> =30V I <sub>D</sub> =200mA, R <sub>GEN</sub> =3.3 Ω, V <sub>GS</sub> =10V)	t <sub>r</sub>	—	20	—	ns
Turn-OFF Delay Time 关断延迟时间 (V <sub>DS</sub> =30V I <sub>D</sub> =200mA, R <sub>GEN</sub> =3.3 Ω, V <sub>GS</sub> =10V)	t <sub>d(off)</sub>	—	15	—	ns
Turn-OFF Fall Time 关断下降时间 (V <sub>DS</sub> =30V I <sub>D</sub> =200mA, R <sub>GEN</sub> =3.3 Ω, V <sub>GS</sub> =10V)	t <sub>f</sub>	—	10	—	ns

■ Dimension 外形封装尺寸



Symbol	Dimensions (mm)	
	Min	Max
A	0.40	0.50
A1	0.00	0.10
b	0.15	0.25
b1	0.20	0.30
c	0.06	0.16
D	1.10	1.30
e	0.8TYP	
E	1.10	1.30
E1	0.70	0.90
θ	8°	10°